



## 20V N-Channel MOSFETs

### General Description

The N1MNB002 is the high cell density trench N-ch MOSFETs, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

$BV_{DSS}$	$R_{DS(ON)}$	$I_D$
20 V	2 m $\Omega$	50 A

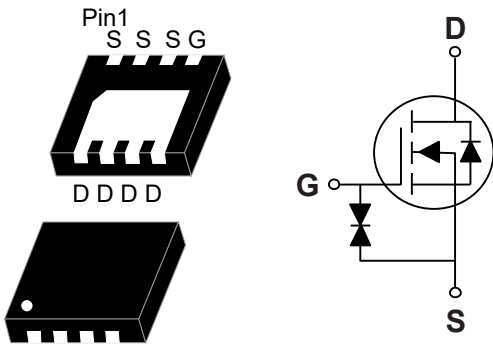
### Features

- $R_{DS(ON)} \leq 2m\Omega @ V_{GS}=4.5V$
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

### Applications

- Load Switch
- Battery Protection
- Hand-Held Instruments

DFN3.3x3.3 Pin Configuration



### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Drain Current - Continuous ( $T_c=25^\circ\text{C}$ )	50	A
	Drain Current - Continuous ( $T_c=100^\circ\text{C}$ )	39	A
$I_{DM}$	Drain Current - Pulsed (NOTE 1)	200	A
EAS	Single Pulse Avalanche Energy (NOTE 2)	80	mJ
IAS	Avalanche Current	40	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ ) (NOTE 3)	83	W
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
Marking Code		NB002 , E2530	

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient (Steady State)	---	55	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	1.5	$^\circ\text{C/W}$

**20V N-Channel MOSFETs****Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=16V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	---	---	1	$\mu A$
		$V_{DS}=16V, V_{GS}=0V, T_J=125^{\circ}\text{C}$	---	---	5	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 10V, V_{DS}=0V$	---	---	$\pm 10$	$\mu A$

**On Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{DS(ON)}$	Static Drain-Source On-Resistance (NOTE 1)	$V_{GS}=4.5V, I_D=20A$	---	1.5	2	m $\Omega$
		$V_{GS}=2.5V, I_D=20A$	---	2.0	2.7	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	0.4	---	1.0	V

**Dynamic and switching Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$Q_g$	Total Gate Charge (10V)	$V_{DS}=15V, V_{GS}=10V, I_D=20A$	---	77	---	nC
$Q_{gs}$	Gate-Source Charge		---	8.7	---	
$Q_{gd}$	Gate-Drain Charge		---	14	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=15V, V_{GS}=10V, R_G=3\Omega, I_D=20A$	---	10.2	---	nS
$T_r$	Rise Time		---	11.7	---	
$T_{d(off)}$	Turn-Off Delay Time		---	56.4	---	
$T_f$	Fall Time		---	16.2	---	
$C_{iss}$	Input Capacitance	$V_{DS}=10V, V_{GS}=0V, F=1\text{MHz}$	---	4307	---	pF
$C_{oss}$	Output Capacitance		---	501	---	
$C_{riss}$	Reverse Transfer Capacitance		---	321	---	

**Drain-Source Diode Characteristics and Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current (NOTE 4)	$V_G=V_D=0V$ , Force Current	---	---	50	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25^{\circ}\text{C}$	---	---	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F=20A, di/dt=100A/\mu s,$	---	22	---	nS
$Q_{rr}$	Reverse Recovery Charge	$T_J=25^{\circ}\text{C}$	---	72	---	nC

**NOTES :**

1. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
2. The EAS data shows Max. rating. The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=40A$ .
3. The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature.
4. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



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## Characteristics Curves

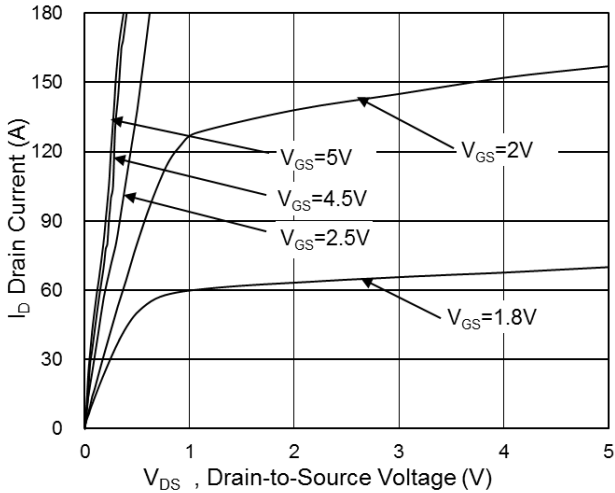


Fig.1 Typical Output Characteristics

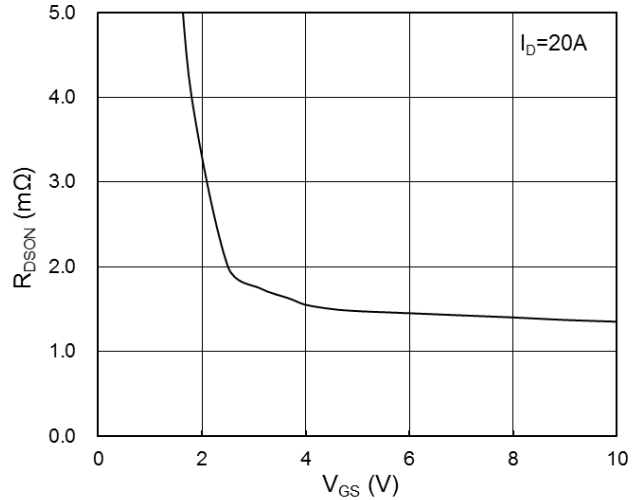


Fig.2 On-Resistance vs. Gate-Source Voltage

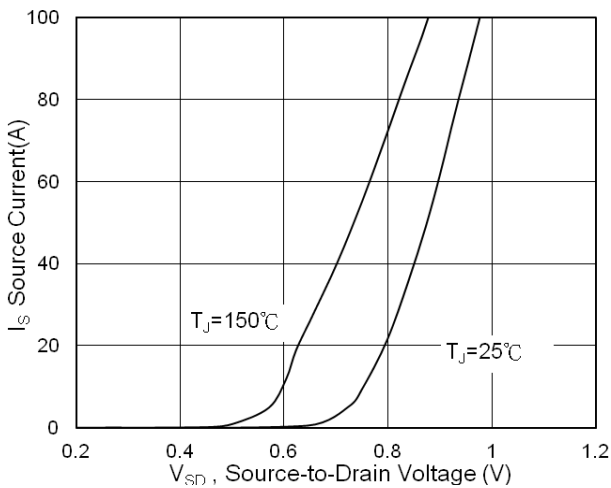


Fig.3 Forward Characteristics of Reverse

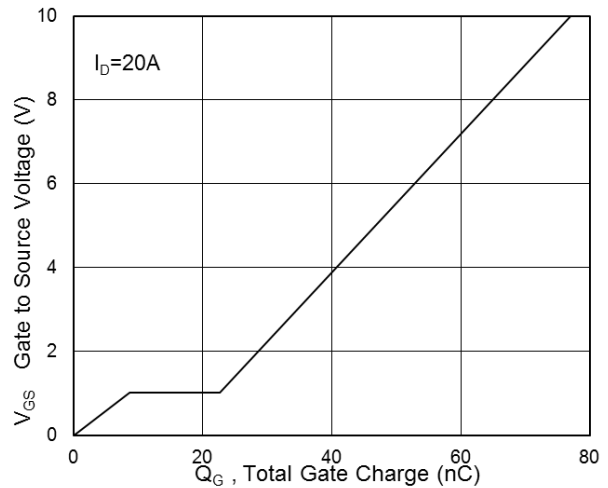


Fig.4 Gate-Charge Characteristics

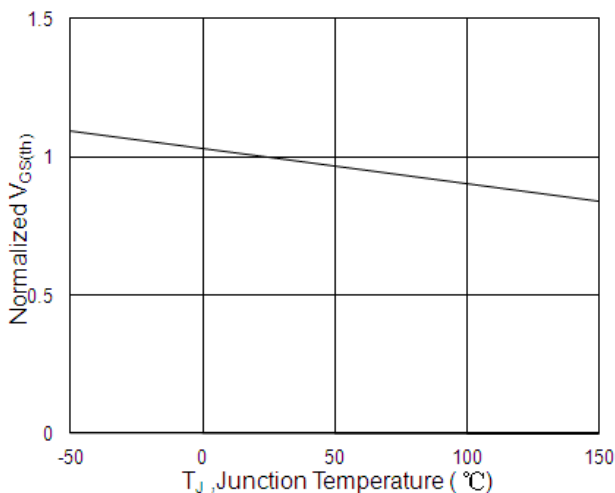


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

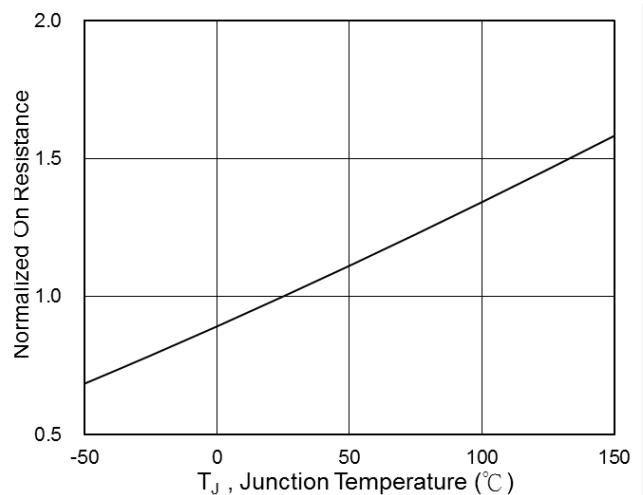


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$



Characteristics Curves

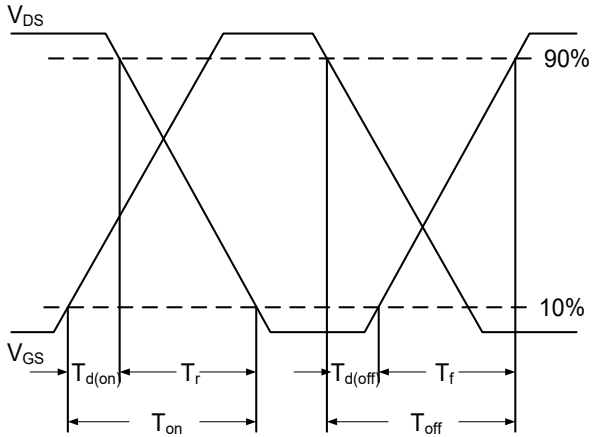
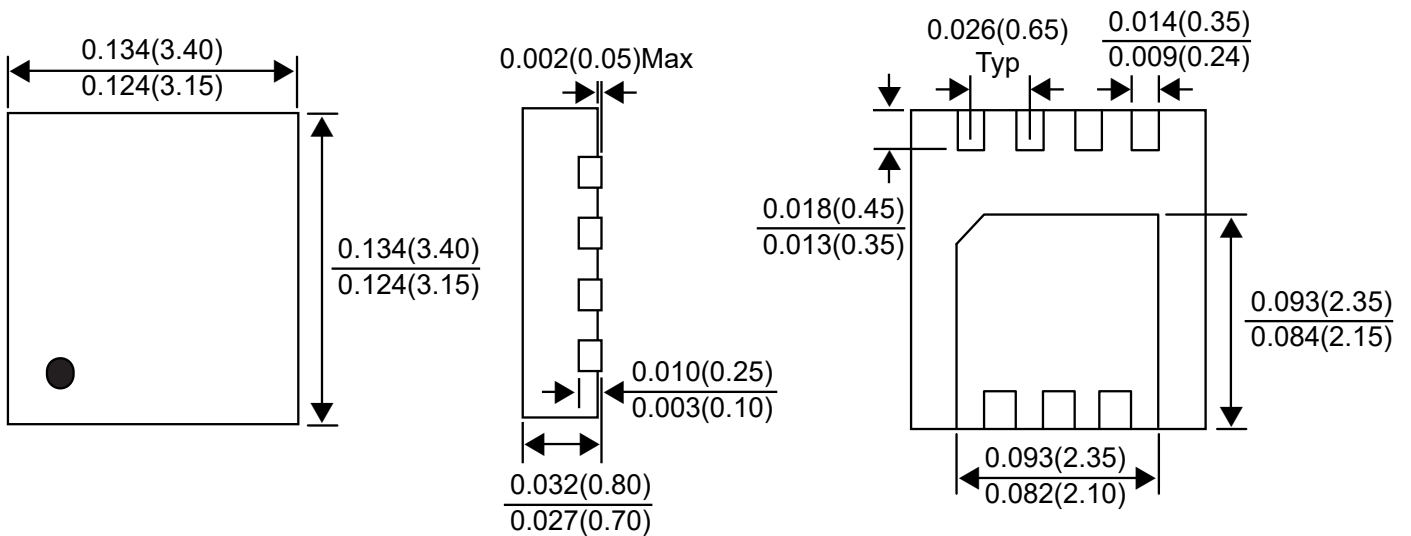


Fig.7 Switching Time Waveform

Package Outline Dimensions



DFN3.3x3.3

Dimensions in inches and (millimeters)



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